

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A method of manufacturing an electronic part in ~~which that side of comprising a conductor film, a lower conductor layer, and an insulating member sandwiched between the conductor film and [[a]] the lower conductor layer which is adjacent to said conductor film, conductor portions connected from said lower conductor layer are exposed, for connecting the conductor film and the lower conductor layer by conductor portions and growing metal plating on the conductor portions and the conductor film, the method comprising:~~

forming a plurality of opening ~~portions~~ holes, each having said lower conductor layer as bottoms ~~in the formed area of said conductor portions, through the conductor film and the insulating member~~ from said conductor film side,

~~growing metal plating layers, as conductor portions~~ from each of the bottoms of said opening ~~portion with holes~~, from said lower conductor layer as an electrode,

~~growing metal plating layers on the upper surfaces of said conductor film and said conductor portions with said conductor film and said conductor portions as electrodes after said conductor portions are formed to the substantial same height~~ in the respective plurality of opening ~~portions holes~~ by growing said metal plating layers so as to contact said metal plating layers with said conductor film, and to increase area for growing said metal plating layers and reduce current density per unit in said metal plating layers, so as to lower growing speed of said metal plating layers, to thereby form said conductor portions in said opening portions holes, and forming a thickness enough to form an upper conductor layer.

Claim 2 (Currently Amended): A method of manufacturing an electronic part in which on the upper surface of an insulating member covering a lower conductor layer,

conductor portions connected from said lower conductor layer are exposed, the method comprising:

forming conductor film on the upper surface of said insulating member and protective film formed on a part of the upper surface of said insulating member and protective film in a thickness direction, and thereafter forming a plurality of opening ~~portions each having holes of which bottom is formed by~~ said lower conductor layer, ~~through as a bottom in~~ said protective film and said conductor film ~~in the formed area of said conductor portion,~~

growing metal plating layers, as said conductor portions from the bottoms of said plurality of opening ~~portions holes~~ with said lower conductor layer as an electrode, and

growing metal plating on the upper surfaces of said conductor film and said conductor portions with said exposed conductor film and said conductor portions on which protective film is not formed as electrodes, to thereby form a thickness enough to form an upper conductor layer after said conductor portions are formed to the substantial same height in the respective plurality of opening ~~portions holes~~ by growing said metal plating layers so as to contact said metal plating layers with said conductor film, and to increase area for growing said metal plating layers and reduce current density per unit in said metal plating layers, so as to lower growing speed of said metal plating layers, to thereby form said conductor portions in said opening ~~portions holes~~.

Claim 3 (Previously Presented): A method according to Claim 1, wherein said exposed conductor film providing said electrode is set outside a product area.

Claim 4 (Previously Presented): A method according to Claim 1, wherein said insulating member and said conductor film are made integral with each other in advance.

Claim 5 (Previously Presented): A method according to Claim 2, wherein said exposed conductor film providing said electrode is set outside a product area.

Claim 6 (Previously Presented): A method according to Claim 2, wherein said insulating member and said conductor film are made integral with each other in advance.